

L Number	Hits	Search Text	DB	Time stamp
1	38	"5252854"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:20
2	35	5252854.URPN.	USPAT	2003/01/23 10:42
3	1	("6081029").PN.	USPAT	2003/01/23 11:25
4	3	6081029.URPN.	USPAT	2003/01/23 11:24
5	1	("6452278").PN.	USPAT	2003/01/23 11:27
6	3153	257/666.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:39
7	144	438/977.ccls. and lead\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:40
8	139	(438/977.ccls. and lead\$2) and (@ad<20000425)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:18
9	1	("20020056926").PN.	US-PGPUB	2003/01/23 11:47
10	1	("6247229").PN.	USPAT	2003/01/23 11:50
11	5	6247229.URPN.	USPAT	2003/01/23 11:48
12	2869	chip and (metal\$4 near (substrate or base)) and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:52
13	436	(chip and (metal\$4 near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:16
14	105	((chip and (metal\$4 near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base))) and encapsula\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:56
15	69	((((chip and (metal\$4 near (substrate or base)) and wire) and ((remov\$3 or thin\$4) near (substrate or base))) and encapsula\$3) and (@ad<20000425)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:59
17	1	("6380062").PN.	USPAT	2003/01/23 12:00
18	2	("5977633"   "6201292").PN.	USPAT	2003/01/23 12:01
19	0	6380062.URPN.	USPAT	2003/01/23 12:03
20	0	6380062.URPN.	USPAT	2003/01/23 12:03
21	0	6380062.URPN.	USPAT	2003/01/23 12:03
16	20	((thick and thin) near lead) and (die or chip) and wire\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 12:04
22	8712	lead and (die or chip) and wire\$5 and encapsula\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 12:05
23	1557	(lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 12:08

24	1102	((lead and (die or chip) and wire\$5 and encapsula\$4) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))) and (@ad<20000425)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 12:28
25	960	((chip or die) near pad) and ((etch\$3 or remov\$3 or thin\$4) near (substrate or base or metal\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 12:47
26	0	20020074672.URPN.	USPAT	2003/01/23 12:43
27	1	("6211462").PN.	USPAT	2003/01/23 13:12
28	0	(think near pad) and lead and (chip or die) and encapsula\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:13
29	21	(thick near pad) and lead and (chip or die) and encapsula\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:15
30	2399	leadless and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:15
32	241	(leadless and chip) and ((remov\$3 or thin\$4) near (metal\$4 or substrate or base))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:18
33	207	((leadless and chip) and ((remov\$3 or thin\$4) near (metal\$4 or substrate or base))) and (@ad<20000425)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:19